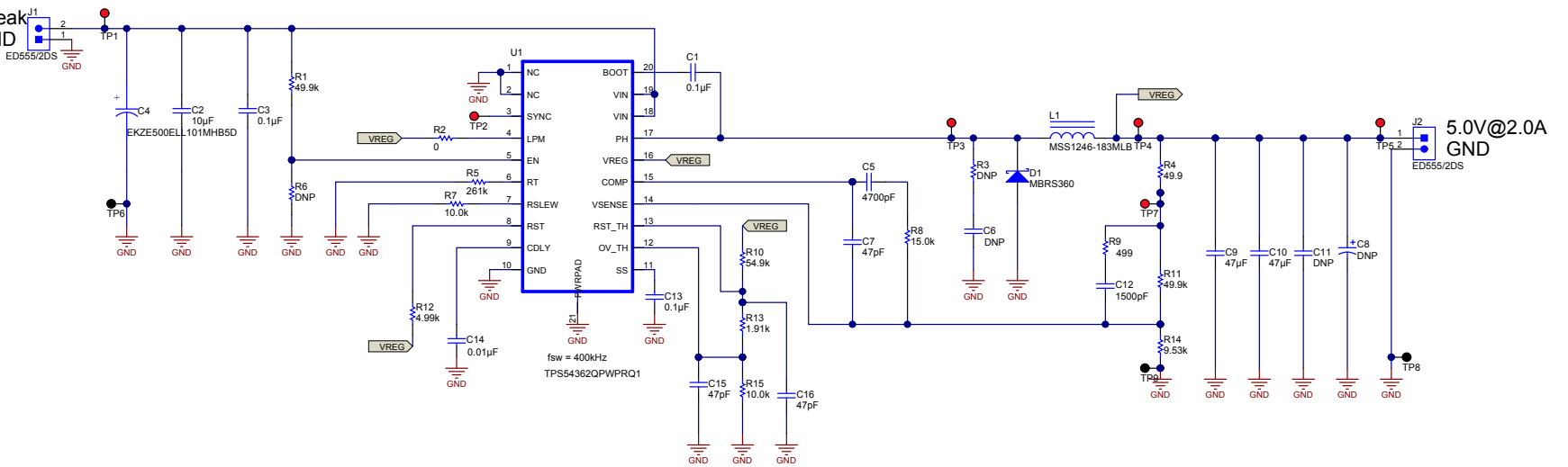


6.0V-18.0V, 42.0V peak

J1

GND



Notes:

- R4 for test purposes only
- DNP = "DO NOT POPULATE"

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Designed for: Public Release		Mod. Date: 2/21/2014	
Project Title:			
Number: PMP10004	Rev: B	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: Variant name not interpreted	
Drawn By:		File: PMP10004_RevB_SchDoc	
Engineer: F. Mueller		Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	
		Sheet: 1 of 1	
		Size: B	

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